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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, LVD, POR, PWM, WDT
Number of I/O	67
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3923 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f86j93t-i-pt

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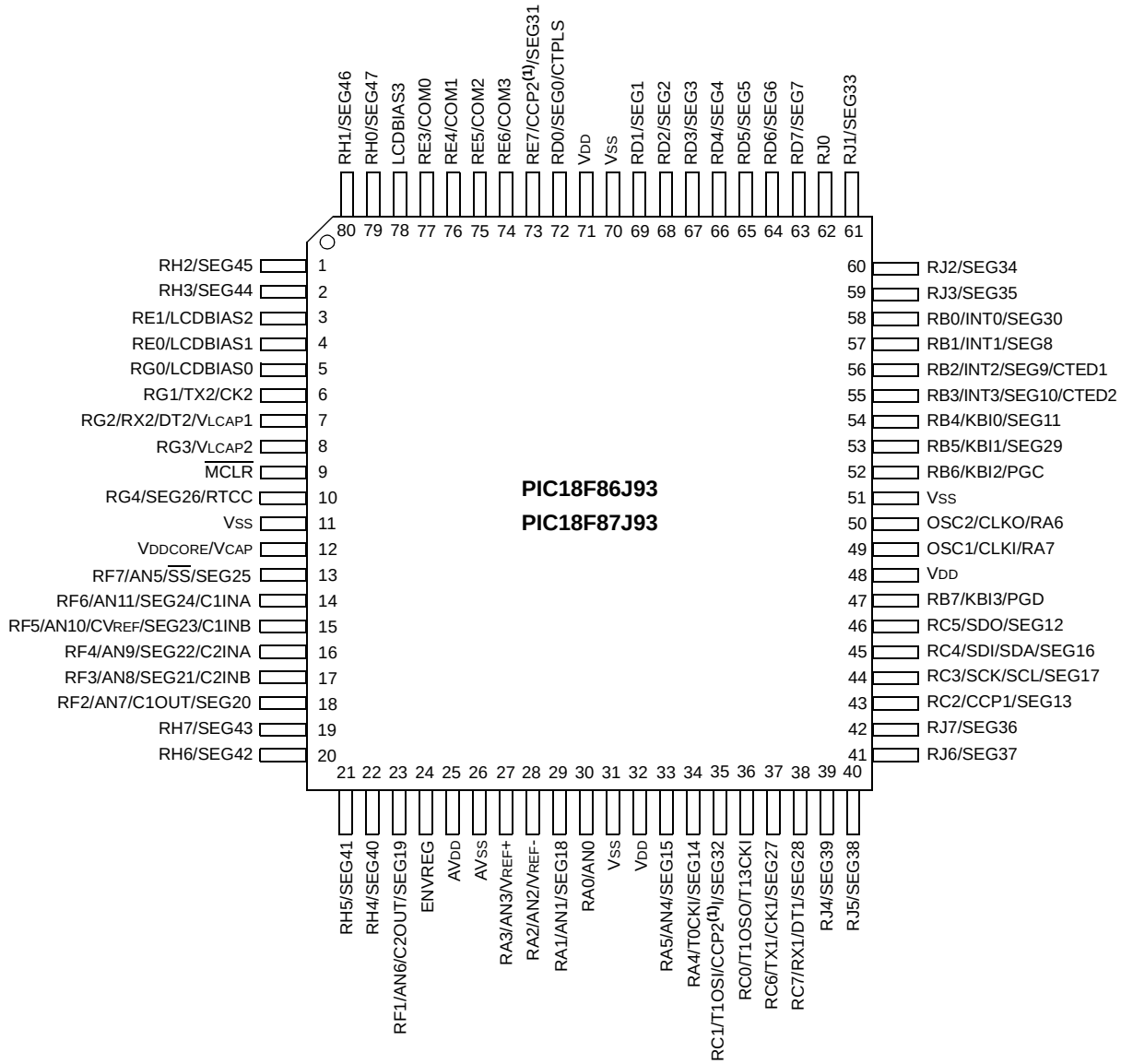
Special Microcontroller Features:

- 10,000 Erase/Write Cycle Flash Program Memory, Typical
- Flash Retention 20 Years, Minimum
- Self-Programmable under Software Control
- Flash Program Memory has Word Write Capability for Data EEPROM Emulators
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 4 ms to 131s
- In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug via Two Pins
- Operating Voltage Range: 2.0V to 3.6V
- 5.5V Tolerant Input (digital pins only)
- Selectable Open-Drain Configuration for Serial Communication and CCP Pins for Driving Outputs up to 5V
- On-Chip 2.5V Regulator

Pin Diagrams – PIC18F8XJ93

80-Pin TQFP



Note 1: The CCP2 pin placement depends on the CCP2MX Configuration bit setting.

TABLE 1-3: PIC18F6XJ93 (64-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	30			
RC0		I/O	ST	Digital I/O.
T1OSO		O	—	Timer1 oscillator output.
T13CKI		I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/SEG32	29			
RC1		I/O	ST	Digital I/O.
T1OSI		I	CMOS	Timer1 oscillator input.
CCP2(1)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG32		O	Analog	SEG32 output for LCD.
RC2/CCP1/SEG13	33			
RC2		I/O	ST	Digital I/O.
CCP1		I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
SEG13		O	Analog	SEG13 output for LCD.
RC3/SCK/SCL/SEG17	34			
RC3		I/O	ST	Digital I/O.
SCK		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL		I/O	ST	Synchronous serial clock input/output for I^2C™ mode.
SEG17		O	Analog	SEG17 output for LCD.
RC4/SDI/SDA/SEG16	35			
RC4		I/O	ST	Digital I/O.
SDI		I	ST	SPI data in.
SDA		I/O	ST	I^2C data I/O.
SEG16		O	Analog	SEG16 output for LCD.
RC5/SDO/SEG12	36			
RC5		I/O	ST	Digital I/O.
SDO		O	—	SPI data out.
SEG12		O	Analog	SEG12 output for LCD.
RC6/TX1/CK1/SEG27	31			
RC6		I/O	ST	Digital I/O.
TX1		O	—	EUSART asynchronous transmit.
CK1		I/O	ST	EUSART synchronous clock (see related RX1/DT1).
SEG27		O	Analog	SEG27 output for LCD.
RC7/RX1/DT1/SEG28	32			
RC7		I/O	ST	Digital I/O.
RX1		I	ST	EUSART asynchronous receive.
DT1		I/O	ST	EUSART synchronous data (see related TX1/CK1).
SEG28		O	Analog	SEG28 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-3: PIC18F6XJ93 (64-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
RE0/LCDBIAS1	2			
RE0		I/O	ST	Digital I/O.
LCDBIAS1		I	Analog	BIAS1 input for LCD.
RE1/LCDBIAS2	1			
RE1		I/O	ST	Digital I/O.
LCDBIAS2		I	Analog	BIAS2 input for LCD.
LCDBIAS3	64	I	Analog	BIAS3 input for LCD.
RE3/COM0	63			
RE3		I/O	ST	Digital I/O.
COM0		O	Analog	COM0 output for LCD.
RE4/COM1	62			
RE4		I/O	ST	Digital I/O.
COM1		O	Analog	COM1 output for LCD.
RE5/COM2	61			
RE5		I/O	ST	Digital I/O.
COM2		O	Analog	COM2 output for LCD.
RE6/COM3	60			
RE6		I/O	ST	Digital I/O.
COM3		O	Analog	COM3 output for LCD.
RE7/CCP2/SEG31	59			
RE7		I/O	ST	Digital I/O.
CCP2(2)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG31		O	Analog	SEG31 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ93 (80-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0/SEG30	58			
RB0		I/O	TTL	Digital I/O.
INT0		I	ST	External Interrupt 0.
SEG30		O	Analog	SEG30 output for LCD.
RB1/INT1/SEG8	57			
RB1		I/O	TTL	Digital I/O.
INT1		I	ST	External Interrupt 1.
SEG8		O	Analog	SEG8 output for LCD.
RB2/INT2/SEG9/CTED1	56			
RB2		I/O	TTL	Digital I/O.
INT2		I	ST	External Interrupt 2.
SEG9		O	Analog	SEG9 output for LCD.
CTED1		I	ST	CTMU Edge 1 input.
RB3/INT3/SEG10/ CTED2	55			
RB3		I/O	TTL	Digital I/O.
INT3		I	ST	External Interrupt 3.
SEG10		O	Analog	SEG10 output for LCD.
CTED2		I	ST	CTMU Edge 2 input.
RB4/KBI0/SEG11	54			
RB4		I/O	TTL	Digital I/O.
KBI0		I	TTL	Interrupt-on-change pin.
SEG11		O	Analog	SEG11 output for LCD.
RB5/KBI1/SEG29	53			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
SEG29		O	Analog	SEG29 output for LCD.
RB6/KBI2/PGC	52			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/KBI3/PGD	47			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ93 (80-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	36			
RC0		I/O	ST	Digital I/O.
T1OSO		O	—	Timer1 oscillator output.
T13CKI		I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/SEG32	35			
RC1		I/O	ST	Digital I/O.
T1OSI		I	CMOS	Timer1 oscillator input.
CCP2(1)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG32		O	Analog	SEG32 output for LCD.
RC2/CCP1/SEG13	43			
RC2		I/O	ST	Digital I/O.
CCP1		I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
SEG13		O	Analog	SEG13 output for LCD.
RC3/SCK/SCL/SEG17	44			
RC3		I/O	ST	Digital I/O.
SCK		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL		I/O	ST	Synchronous serial clock input/output for I^2C™ mode.
SEG17		O	Analog	SEG17 output for LCD.
RC4/SDI/SDA/SEG16	45			
RC4		I/O	ST	Digital I/O.
SDI		I	ST	SPI data in.
SDA		I/O	ST	I^2C data I/O.
SEG16		O	Analog	SEG16 output for LCD.
RC5/SDO/SEG12	46			
RC5		I/O	ST	Digital I/O.
SDO		O	—	SPI data out.
SEG12		O	Analog	SEG12 output for LCD.
RC6/TX1/CK1/SEG27	37			
RC6		I/O	ST	Digital I/O.
TX1		O	—	EUSART asynchronous transmit.
CK1		I/O	ST	EUSART synchronous clock (see related RX1/DT1).
SEG27		O	Analog	SEG27 output for LCD.
RC7/RX1/DT1/SEG28	38			
RC7		I/O	ST	Digital I/O.
RX1		I	ST	EUSART asynchronous receive.
DT1		I/O	ST	EUSART synchronous data (see related TX1/CK1).
SEG28		O	Analog	SEG28 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ93 (80-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/SEG0/CTPLS	72			
RD0		I/O	ST	Digital I/O.
SEG0		O	Analog	SEG0 output for LCD.
CTPLS		O	ST	CTMU pulse generator output.
RD1/SEG1	69			
RD1		I/O	ST	Digital I/O.
SEG1		O	Analog	SEG1 output for LCD.
RD2/SEG2	68			
RD2		I/O	ST	Digital I/O.
SEG2		O	Analog	SEG2 output for LCD.
RD3/SEG3	67			
RD3		I/O	ST	Digital I/O.
SEG3		O	Analog	SEG3 output for LCD.
RD4/SEG4	66			
RD4		I/O	ST	Digital I/O.
SEG4		O	Analog	SEG4 output for LCD.
RD5/SEG5	65			
RD5		I/O	ST	Digital I/O.
SEG5		O	Analog	SEG5 output for LCD.
RD6/SEG6	64			
RD6		I/O	ST	Digital I/O.
SEG6		O	Analog	SEG6 output for LCD.
RD7/SEG7	63			
RD7		I/O	ST	Digital I/O.
SEG7		O	Analog	SEG7 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD})

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ93 (80-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTG is a bidirectional I/O port.
RG0/LCDBIAS0	5			
RG0		I/O	ST	Digital I/O.
LCDBIAS0		I	Analog	BIAS0 input for LCD.
RG1/TX2/CK2	6			
RG1		I/O	ST	Digital I/O.
TX2		O	—	AUSART asynchronous transmit.
CK2		I/O	ST	AUSART synchronous clock (see related RX2/DT2).
RG2/RX2/DT2/VLCAP1	7			
RG2		I/O	ST	Digital I/O.
RX2		I	ST	AUSART asynchronous receive.
DT2		I/O	ST	AUSART synchronous data (see related TX2/CK2).
VLCAP1		I	Analog	LCD charge pump capacitor input.
RG3/VLCAP2	8			
RG3		I/O	ST	Digital I/O.
VLCAP2		I	Analog	LCD charge pump capacitor input.
RG4/SEG26/RTCC	10			
RG4		I/O	ST	Digital I/O.
SEG26		O	Analog	SEG26 output for LCD.
RTCC		O	—	RTCC output.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD)

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

TABLE 1-4: PIC18F8XJ93 (80-PIN DEVICE) PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTJ is a bidirectional I/O port.
RJ0	62	I/O	ST	Digital I/O.
RJ1/SEG33	61			
RJ1		I/O	ST	Digital I/O.
SEG33		O	Analog	SEG33 output for LCD.
RJ2/SEG34	60			
RJ2		I/O	ST	Digital I/O.
SEG34		O	Analog	SEG34 output for LCD.
RJ3/SEG35	59			
RJ3		I/O	ST	Digital I/O.
SEG35		O	Analog	SEG35 output for LCD.
RJ4/SEG39	39			
RJ4		I/O	ST	Digital I/O.
SEG39		O	Analog	SEG39 output for LCD.
RJ5/SEG38	40			
RJ5		I/O	ST	Digital I/O
SEG38		O	Analog	SEG38 output for LCD.
RJ6/SEG37	41			
RJ6		I/O	ST	Digital I/O.
SEG37		O	Analog	SEG37 output for LCD.
RJ7/SEG36	42			
RJ7		I/O	ST	Digital I/O.
SEG36		O	Analog	SEG36 output for LCD.
VSS	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVSS	26	P	—	Ground reference for analog modules.
AVDD	25	P	—	Positive supply for analog modules.
ENVREG	24	I	ST	Enable for on-chip voltage regulator.
VDDCORE/VCAP	12			Core logic power or external filter capacitor connection.
VDDCORE		P	—	Positive supply for microcontroller core logic (regulator disabled).
VCAP		P	—	External filter capacitor connection (regulator enabled).

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD)

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

REGISTER 2-2: ADCON1: A/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRIGSEL	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **TRIGSEL:** Special Trigger Select bit
1 = Selects the special trigger from the CTMU
0 = Selects the special trigger from the CCP2

bit 6 **Unimplemented:** Read as '0'

bit 5 **VCFG1:** Voltage Reference Configuration bit (V_{REF-} source)
1 = V_{REF-} (AN2)
0 = AV_{SS}

bit 4 **VCFG0:** Voltage Reference Configuration bit (V_{REF+} source)
1 = V_{REF+} (AN3)
0 = AV_{DD}

bit 3-0 **PCFG<3:0>:** A/D Port Configuration Control bits:

PCFG<3:0>	AN11	AN10	AN9	AN8	AN7	AN6	AN5	AN4	AN3	AN2	AN1	AN0
0000	A	A	A	A	A	A	A	A	A	A	A	A
0001	A	A	A	A	A	A	A	A	A	A	A	A
0010	A	A	A	A	A	A	A	A	A	A	A	A
0011	A	A	A	A	A	A	A	A	A	A	A	A
0100	D	A	A	A	A	A	A	A	A	A	A	A
0101	D	D	A	A	A	A	A	A	A	A	A	A
0110	D	D	D	A	A	A	A	A	A	A	A	A
0111	D	D	D	D	A	A	A	A	A	A	A	A
1000	D	D	D	D	D	A	A	A	A	A	A	A
1001	D	D	D	D	D	D	A	A	A	A	A	A
1010	D	D	D	D	D	D	D	A	A	A	A	A
1011	D	D	D	D	D	D	D	D	A	A	A	A
1100	D	D	D	D	D	D	D	D	D	A	A	A
1101	D	D	D	D	D	D	D	D	D	D	A	A
1110	D	D	D	D	D	D	D	D	D	D	D	A
1111	D	D	D	D	D	D	D	D	D	D	D	D

A = Analog input D = Digital I/O

2.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Equation 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 2-1: ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$

EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$

or

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2048)$$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$

$$T_{AMP} = 0.2\ \mu s$$

$$T_{COFF} = (Temp - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2048)\ \mu s$$
$$-(25\ pF)\ (1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega) \ln(0.0004883)\ \mu s$$
$$1.05\ \mu s$$

$$T_{ACQ} = 0.2\ \mu s + 1\ \mu s + 1.2\ \mu s$$
$$2.4\ \mu s$$

2.2 Selecting and Configuring Automatic Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set.

When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This occurs when the ACQT<2:0> bits (ADCON2<5:3>) remain in their Reset state ('000') and is compatible with devices that do not offer programmable acquisition times.

If desired, the ACQT bits can be set to select a programmable acquisition time for the A/D module. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 11 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable.

There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible but greater than the minimum TAD.

Table 2-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-1: TAD VS. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Maximum Device Frequency
Operation	ADCS<2:0>	
2 TOSC	000	2.86 MHz
4 TOSC	100	5.71 MHz
8 TOSC	001	11.43 MHz
16 TOSC	101	22.86 MHz
32 TOSC	010	40.0 MHz
64 TOSC	110	40.0 MHz
RC(2)	x11	1.00 MHz(1)

Note 1: The RC source has a typical TAD time of 4 μs.

2: For device frequencies above 1 MHz, the device must be in Sleep mode for the entire conversion or the A/D accuracy may be out of specification.

2.4 Configuring Analog Port Pins

The ADCON1, TRISA, TRISF and TRISH registers control the operation of the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS<3:0> bits and the TRIS bits.

Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs will convert an analog input. Analog levels on a digitally configured input will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

2.5 A/D Conversions

Figure 2-3 shows the operation of the A/D converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT<2:0> bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-4 shows the operation of the A/D converter after the GO/$\overline{\text{DONE}}$ bit has been set; the ACQT<2:0> bits are set to '010' and a 4 TAD acquisition time is selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TAD wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

2.6 Use of the CCP2 Trigger

An A/D conversion can be started by the "Special Event Trigger" of the CCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate TACQ time is selected before the Special Event Trigger sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module but will still reset the Timer1 (or Timer3) counter.

FIGURE 2-3: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

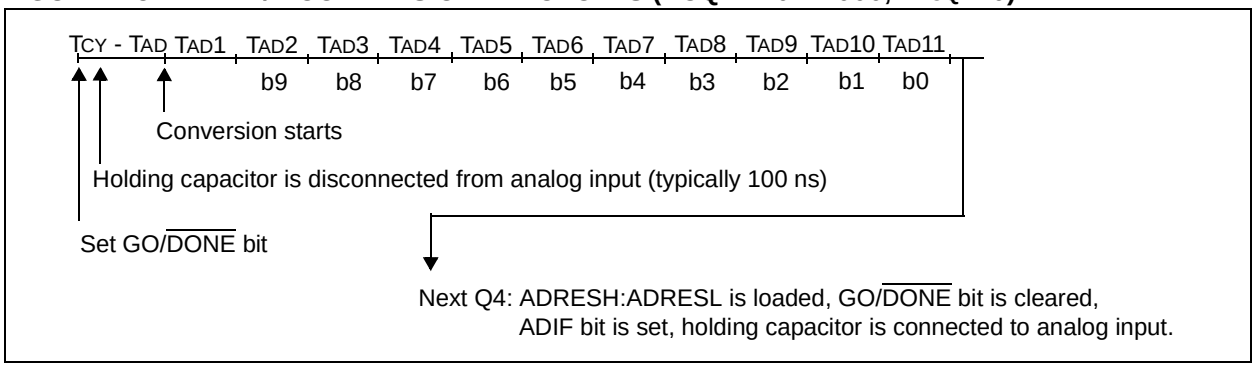
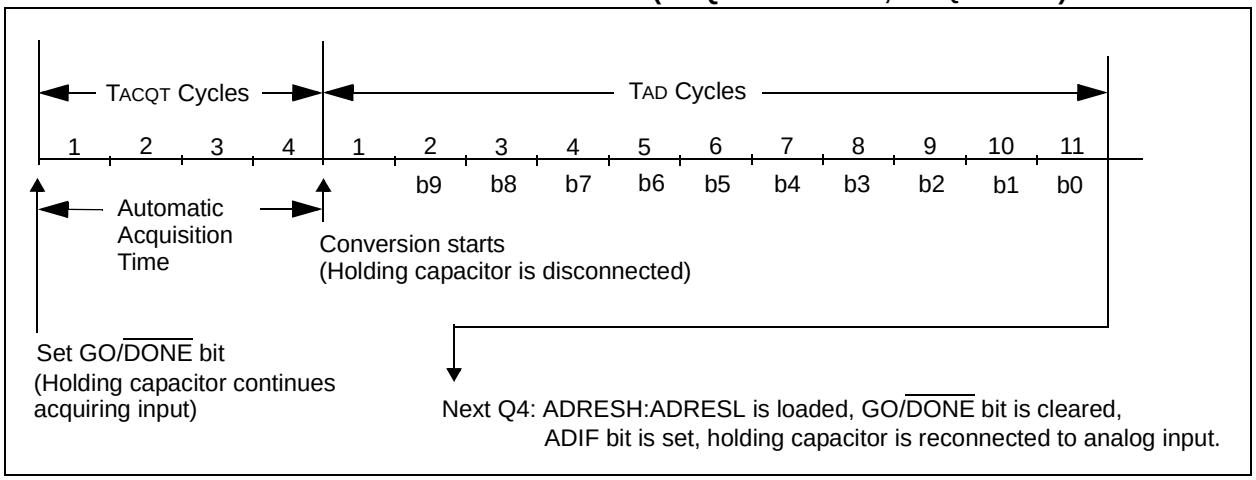


FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)



NOTES:

3.0 SPECIAL FEATURES OF THE CPU

Note 1: This section documents only the CPU features that are different from, or in addition to, the features of the PIC18F87J90 family devices.

2: For additional details on the Configuration bits, refer to **Section 24.1 "Configuration Bits"** in the *"PIC18F87J90 Family Data Sheet"* (DS39933).

3.1 Device ID Registers

The Device ID registers are "read-only" registers. They identify the device type and revision for device programmers and can be read by firmware using table reads.

TABLE 3-1: DEVICE ID REGISTERS

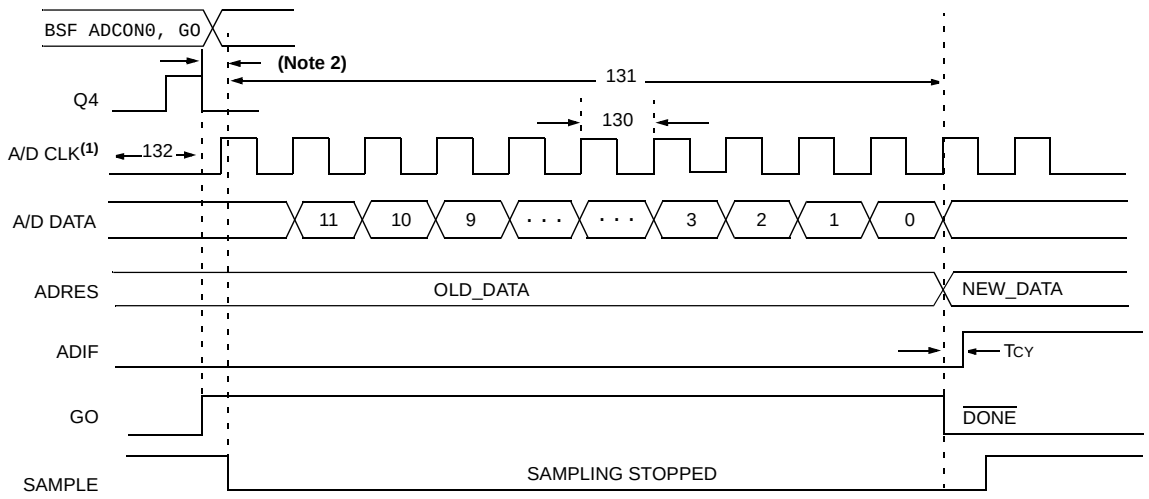
File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value(1)
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx(2)
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	0000 10x1(2)

Legend: x = unknown, – = unimplemented. Shaded cells are unimplemented, read as '0'.

Note 1: Values reflect the unprogrammed state as received from the factory and following Power-on Resets. In all other Reset states, the configuration bytes maintain their previously programmed states.

2: See Register 3-1 and Register 3-2 for DEVID values. These registers are read-only and cannot be programmed by the user.

FIGURE 4-3: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

2: This is a minimal RC delay (typically 100 ns), which also disconnects the holding capacitor from the analog input.

TABLE 4-2: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic	Min	Max	Units	Conditions
130	TAD	A/D Clock Period	0.8	12.5(1)	µs	TOSC based, VREF ≥ 3.0V
131	TCNV	Conversion Time (not including acquisition time)(2)	13	14	TAD	
132	TACQ	Acquisition Time(3)	1.4	—	µs	
135	TSWC	Switching Time from Convert → Sample	—	**(Note 4)**		
137	TDIS	Discharge Time	0.2	—	µs	

Note 1: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

2: ADRES registers may be read on the following TCY cycle.

3: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (RS) on the input channels is 50Ω.

4: On the following cycle of the device clock.

5.0 PACKAGING INFORMATION

For packaging information, see the *"PIC18F87J93 Family Data Sheet"* (DS39933).

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain purchasing information such as pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device[1,2]	PIC18F66J93, PIC18F66J93T PIC18F67J93, PIC18F67J93T PIC18F86J93, PIC18F86J93T PIC18F87J93, PIC18F87J93T
Temperature Range	I = -40°C to +85°C (Industrial)
Package	PT = TQFP (Thin Quad Flatpack)
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18F87J93-I/PT 301 = Industrial temperature, TQFP package, QTP pattern #301.

b) PIC18F87J93T-I/PT = Tape and reel, Industrial temperature, TQFP package.

Note 1: F = Standard Voltage Range
2: T = In Tape and Reel